

	Professional Development Course Name	Instructor	
June 1: 10:00-1:00 ET	1. ACHIEVING HIGH RELIABILITY OF LEAD-FREE SOLDER JOINTS – MATERIALS CONSIDERATIONS	Ning-Cheng Lee	
June 14: 10:00-1:00 ET	3. FUNDAMENTALS OF RF DESIGN AND FABRICATION PROCESSES OF FAN-OUT WAFER PANEL LEVEL PACKAGES AND INTERPOSERS	Ivan Ndip & Markus Wöhrmann	
June 2: 7:00-10:00 PM ET	2. FUNDAMENTALS OF GLASS TECHNOLOGY AND APPLICATIONS FOR ADVANCED SEMICONDUCTOR PACKAGING	Prakash Gajendra & Joseph Canale	
June 3: 10:00-1:00 ET	5. CHARACTERIZATION OF ADVANCED EMCs FOR FO-WLP, HETEROGENEOUS INTEGRATION, AND AUTOMOTIVE ELECTRONICS	Przemyslaw Gromala	
June 3: 7:00-10:00 PM ET	4. ELIMINATING PACKAGE FAILURE MECHANISMS FOR IMPROVED RELIABILITY	Darvin Edwards	
June 4: 10:00-1:00 ET	6. RELIABLE INTEGRATED THERMAL PACKAGING FOR POWER ELECTRONICS	Patrick McCluskey	
June 7: 10:00-1:00 ET	7. FLIP CHIP TECHNOLOGIES	Eric Perfecto & Shengmin Wen	
June 8: 10:00-1:00 ET	8. WAFER-LEVEL CHIP-SCALE PACKAGING (WCSP) FUNDAMENTALS	Patrick Thompson	
June 8: 7:00-10:00 PM ET	9. ADDITIVE FLEXIBLE HYBRID ELECTRONICS – MANUFACTURING AND RELIABILITY	Pradeep Lall	
June 9: 10:00-1:00 ET	11. POLYMERS IN WAFER LEVEL PACKAGING	Jeffrey Gotro	
June 9: 7:00-10:00 PM ET	10. FAN-OUT WAFER PANEL LEVEL PACKAGING AND 3D CHIPLET HETEROGENEOUS INTEGRATION	John Lau	
June 10: 7:00-10:00 PM ET	12. RELIABILITY MECHANICS AND MODELING FOR IC PACKAGING	Ricky Lee & Xuejun Fan	
June 10: 10:00-1:00 ET	13. FROM WAFER TO PANEL LEVEL PACKAGING	Tanja Braun & Michael Töpper	
June 11: 10:00-1:00 ET	14. THERMAL MANAGEMENT OF ELECTRONICS	Jaime Sanchez	